



Premstaetten, July 3, 2020

PCN34-2020 (NanEye Die Packaging)

Dear Customer,

Please be informed about the upcoming change on the method and material used for the packaging of the NanEye2D Dies.

Change Description

While transferring the CSP production from IZM (Institute) to our qualified OSAT Xintec, the product MSL classification was updated to MSL3. In light of this update and the applicable industry standard requirements of packing Moisture Sensitive Devices, AMS introduced a dry baking step for the NanEye2D Dies prior shipment to our clients. As a consequence of this extra step, an update of the current packaging tray to a 4" waffle tray that can sustain the dry baking requirements of 125 degree Celsius for 8h will be implemented.

Impact on packing & shipment

A new packaging specification QTY-1167 has been reviewed accordingly.

Implementation plan

ams AG plans to implement this change by end-July, 2020.

The following products will be affected

Material Part Number	Material Description
301200033	NE2D_CHIP_B&W_SGA CON FT SE
301190021	NE2D_CHIP_RGB_SGA CON FT SE



Please be advised that unless ams receive your written refusal concerning this change notification within 30 days, the change notification shall be deemed accepted.

If you do have further questions, please do not hesitate to contact ams team at any time.

Best regards,

A handwritten signature in black ink, appearing to read 'Peter Crabbe', with a stylized flourish at the end.

Peter Crabbe
ams AG
Director Operations CIS